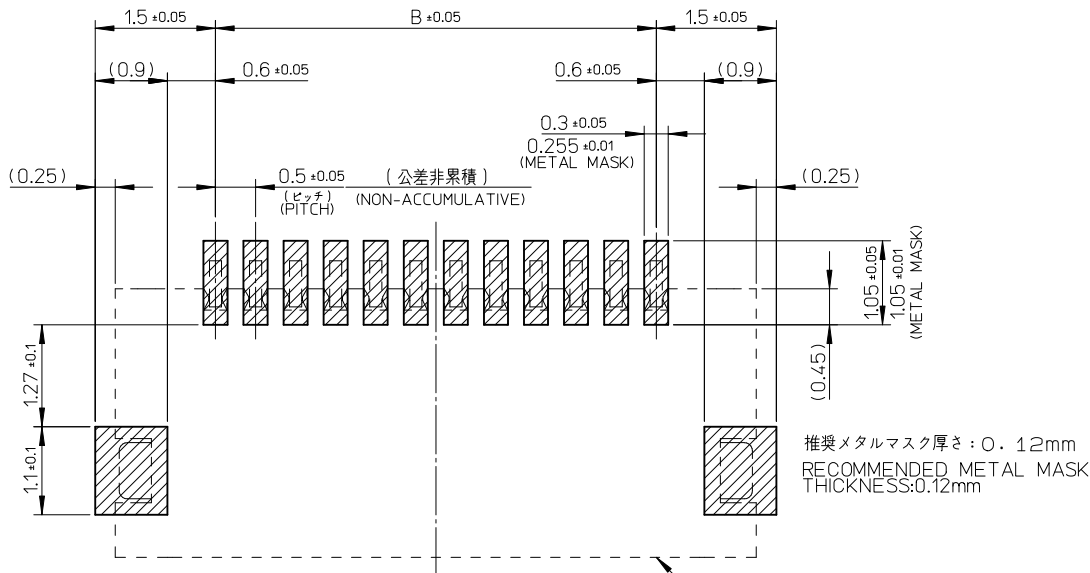


23	22	24.5	502118-4591	45
C	B	A	EMBOSSED PACKAGING	極数
			オーダー番号 ORDER NO.	CIRCUITS

CONNECTOR SERIES NO. : 502118-\*\*-21

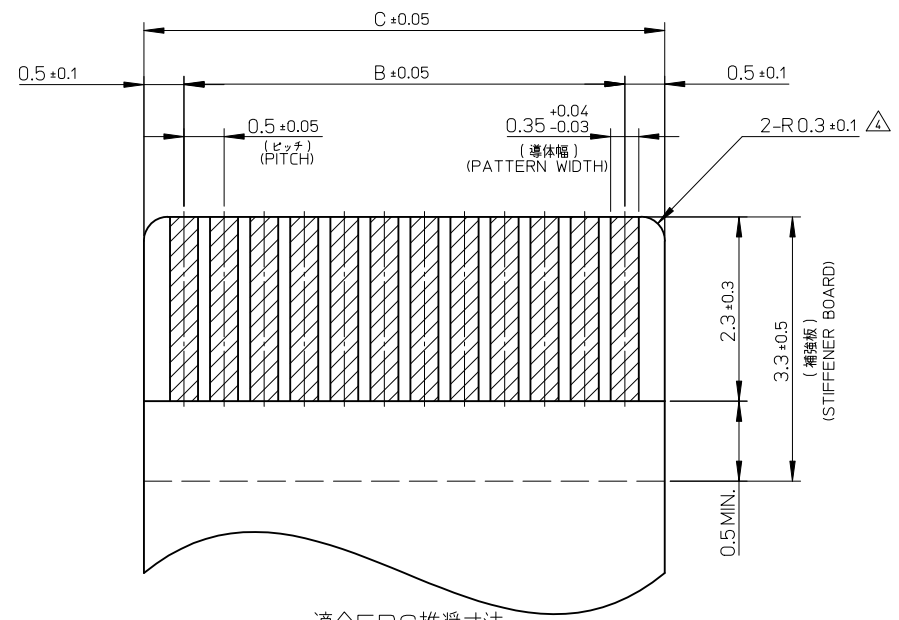
RELEASED EC NO: J2010-1059 DRWN:HON001 2009/11/19 CHKD:HSHIMOYAMA 2009/11/19 APPR:KNORIKAWA 2009/11/19	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
			MM ONLY	///	METRIC		
	10 UNDER	± 0.2	DRAWN BY	DATE	TITLE	0.5 FPC CONN BACK FLIP H=0.9 UPR/BTM CONT  <b>molex</b> MOLEX INCORPORATED DOCUMENT NO. SD-502118-003 SHEET NO. 1 OF 2	
	10 OVER 30 UNDER	± 0.25	HONO	2008/11/19			
	30 OVER	± 0.3	HSHIMOYAMA	2008/11/19			
ANGULAR	± 1 °	APPROVED BY	DATE				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		HHIRATA	2008/11/19				
		SEE CHART					
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



推奨基板レイアウト  
RECOMMENDED P.W. BOARD  
PATTERN DIMENSION  
(マウント面)  
(MOUNTING SIDE)

コネクタ位置  
CONNECTOR POSITION

推奨メタルマスク厚さ: 0.12mm  
RECOMMENDED METAL MASK  
THICKNESS: 0.12mm



適合FPC推奨寸法  
APPLICABLE FPC  
RECOMMENDED DIMENSION  
(仕上がり厚さ: 0.20 ± 0.03)  
(THICKNESS: 0.20 ± 0.03)

注記 NOTE

1. 使用材料 MATERIAL

- ハウジング HOUSING : 液晶ポリマー, 色: 白  
ガラス充填, UL94V-0  
LIQUID CRYSTAL POLYMER, COLOR: WHITE  
GLASS FILLED, UL94V-0
- アクチュエータ ACTUATOR : ポリアミド樹脂, 色: 黒  
ガラス充填, UL94V-0  
POLYAMIDE, COLOR: BLACK  
GLASS FILLED, UL94V-0
- ターミナル TERMINAL : りん青銅 (t=0.15)  
PHOSPHOR BRONZE (t=0.15)
- 補強金具 FITTING NAIL : りん青銅 (t=0.15)  
PHOSPHOR BRONZE (t=0.15)

- 3. 端子、補強金具の平坦度は0.1以下とする。  
SOLDER TAILS AND FITTING NAILS  
COPLANARITY TO BE 0.1 MAXIMUM.
- △ R0.3はFPC導体部にかからないこと。  
R0.3 MUST NOT BE OVERLAPPED  
TO PATTERN OF FPC.
- 5. ELV及びRoHS適合品  
ELV AND RoHS COMPLIANT.
- 6. 基板実装前にアクチュエータを操作しないで下さい。  
必ず基板に実装し、FPCを挿入してからアクチュエータを操作して下さい。  
PLEASE DO NOT OPERATE THE ACTUATOR  
BEFORE MOUNTING.  
PLEASE OPERATE THE ACTUATOR AFTER MOUNTING ON  
THE SUBSTRATE, AND MATING FPC.

FPCについて  
ABOUT FPC

抜き方向は、導体側から補強板を推奨します。  
補強板材質は、ポリイミドを推奨します。  
接着剤は熱硬化接着剤を推奨します。  
なお、接着剤の接点部への付着は導通不良の  
原因となりますので染み出しの無いよう、お願いします。

RECOMMENDED PUNCHER DIRECTION :  
FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.  
RECOMMENDED MATERIAL :  
STIFFENER BOARD : POLYIMIDE  
BONDING AGENT : THERMOSETTING AGENT  
PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND  
BECAUSE THERE IS A POSSIBILITY  
THAT THE EXTRA ADHESIVE CAUSES THE DEFECT  
IN ELECTRICAL CONTINUITY.

2. めっき仕様 PLATING

- ターミナル TERMINAL : コンタクト部: 金めっき (0.1 µm以上)  
テール部: 金めっき  
下地: ニッケルめっき (1.0 µm以上)  
CONTACT AREA: GOLD PLATING (0.1 µm MINIMUM)  
SOLDER TAIL AREA: GOLD PLATING  
UNDER PLATE: NICKEL PLATING (1.0 µm MINIMUM)
- 補強金具 FITTING NAIL : 仕上: 錫めっき (1.0 µm以上)  
下地: ニッケルめっき (1.0 µm以上)  
PALTE: TIN PLATING (1.0 µm MINIMUM)  
UNDER PLATE: NICKEL PLATING (1.0 µm MINIMUM)

RELEASED IEC NO: J2010-1059 2009/11/19 DRW: HON001 2009/11/19 CHK: HSHIMOMIYAMA 2009/11/19 APPR: KNORIKAWA 2009/11/19	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE //	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± 0.2	DRAWN BY HONO	DATE 2008/11/19	TITLE 0.5 FPC CONN BACK FLIP H=0.9 UPR/BTM CONT		
	10 OVER 30 UNDER	± 0.25	CHECKED BY HSHIMOMIYAMA	DATE 2008/11/19	MOLEX INCORPORATED		
	30 OVER	± 0.3	APPROVED BY HHIRATA	DATE 2008/11/19			
ANGULAR ±1 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-502118-003		2 OF 2	
SIZE A3 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							

F

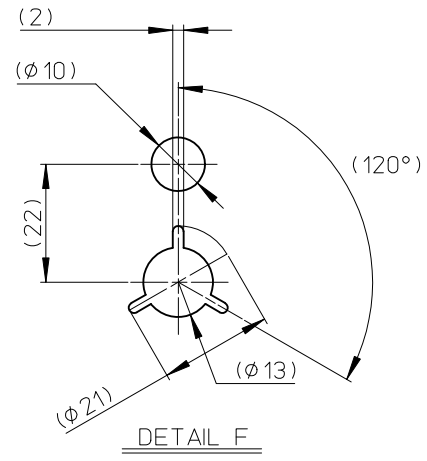
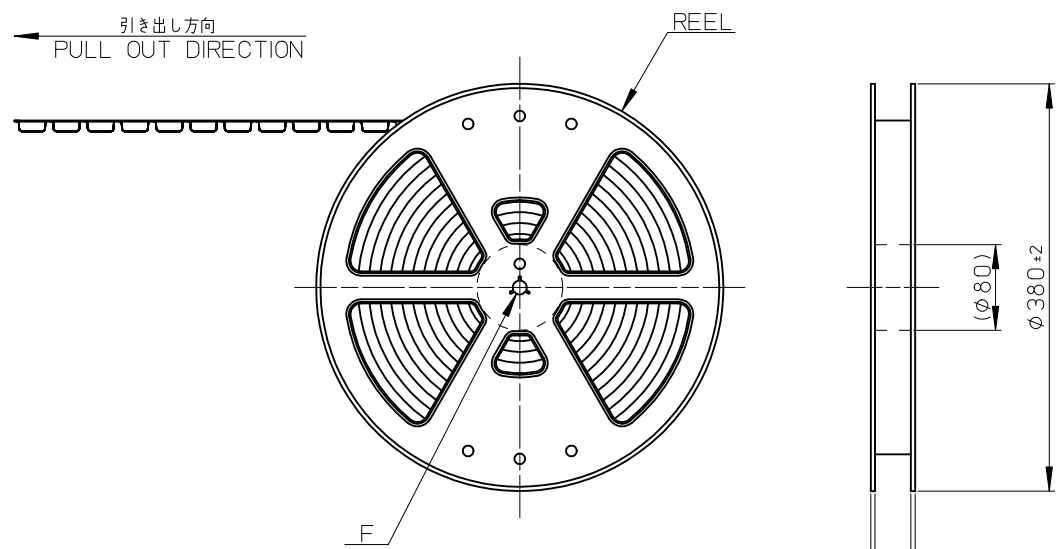
E

D

C

B

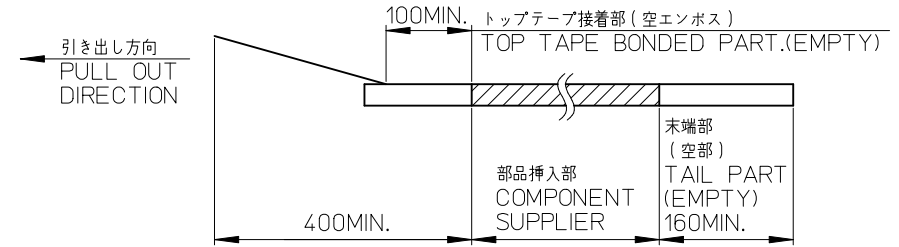
A



C±1  
D±1

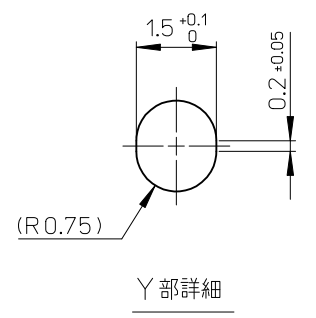
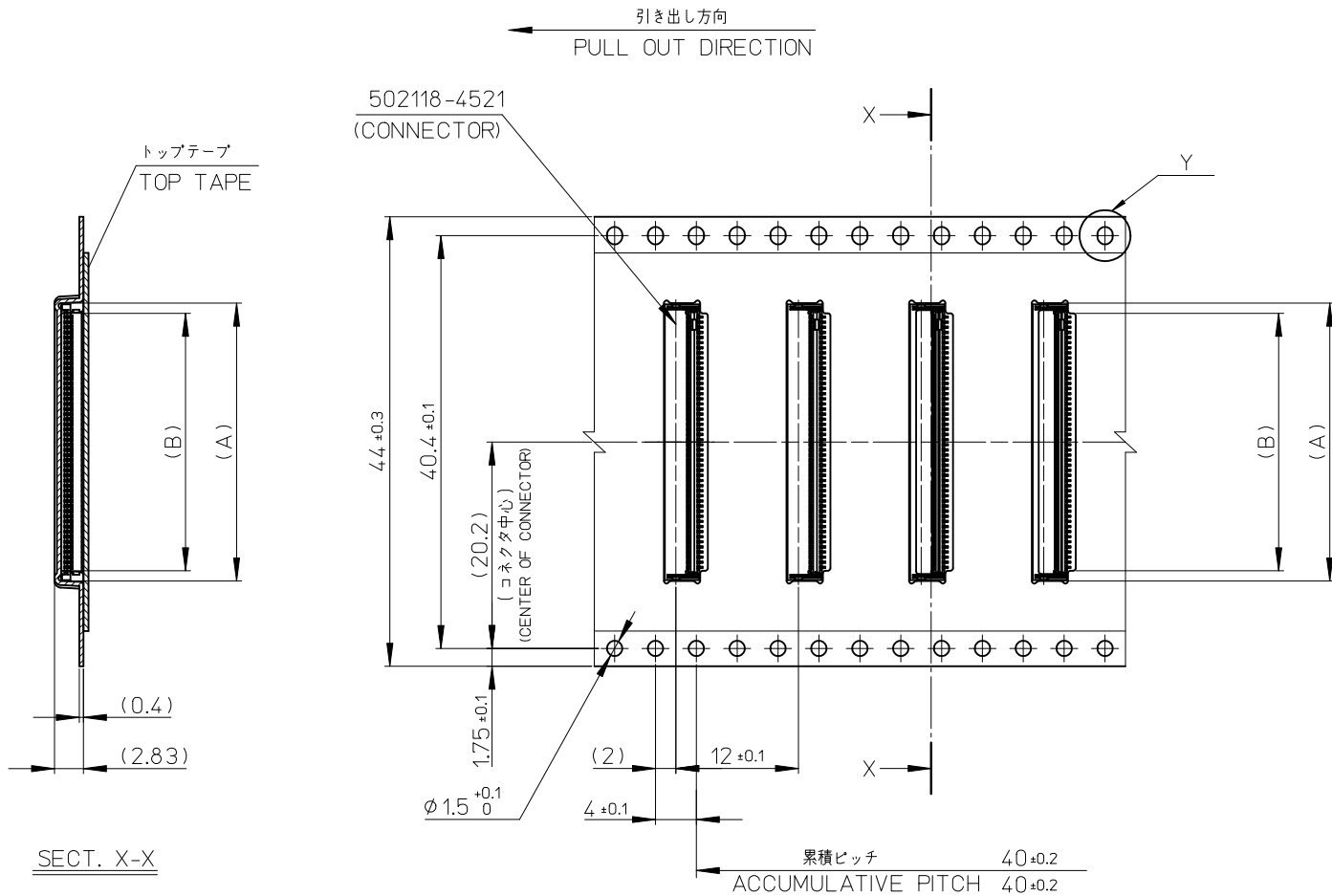
NOTES

- 製品詳細寸法については製品単体図面を参照下さい。  
RE DETAILED DIMENSION, SEE PRODUCT DRAWING.
- 梱包数量: 2500個/リール  
NUMBER OF CONNECTORS 2500PCS/REEL
- リードテープ長さ  
LEAD TAPE LENGTH



- 材料  
MATERIAL  
キャリアテープ(CARRIRE TAPE): ポリスチレン (POLYSTYRENE)  
トップテープ(TOP TAPE): PET, PE, PEF  
リール(REEL): ポリスチレン (PS) <リサイクル材を含む>  
POLYSTYRENE(PS) <RECYCLE MATERIAL CONTAILED>
- ELV及びRoHS適合品  
ELV AND RoHS COMPLIANT.

RELEASED EC NO: J2010-1059 DRWN:HONO01 2009/11/19 CH'KD:HSHIMOYAMA 2009/11/19 APPR:KNORIKAWA 2009/11/19	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±---	DRAWN BY HONO	DATE 2008/11/19	TITLE 0.5 FPC CONN BACK FLIP H=0.9 UPR/BTM CONT EMBSTP PKG			
	10 OVER 30 UNDER	±---	CHECKED BY HSHIMOYAMA	DATE 2008/11/19	APPROVED BY HIRATA 2008/11/19			
	30 OVER	±---	MATERIAL NO. SEE CHART		DOCUMENT NO. SD-502118-004		SHEET NO. 1 OF 2	
	ANGULAR ±--- °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



SECT. X-X

44	49.4	45.4	22.7	24.7	502118-4591	45
キャリアテープ幅 CARRIER TAPE WIDTH	D	C	(B)	(A)	製品番号 MATERIAL NO.	極数 CIRCUITS

RELEASED EC NO: J2010-1059 DRWN: HON001 CHKD: HSHIMOYAMA APPR: KMORIKAWA	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± ---	DRAWN BY HONO	DATE 2008/11/19	TITLE 0.5 FPC CONN BACK FLIP H=0.9 UPR/BTM CONT EMBSTP PKG		
	10 OVER 30 UNDER	± ---	CHECKED BY HSHIMOYAMA	DATE 2008/11/19	MOLEX MOLEX INCORPORATED		
	30 OVER	± ---	APPROVED BY HHIRATA	DATE 2008/11/19	DOCUMENT NO. SD-502118-004	SHEET NO. 2 OF 2	
	ANGULAR	± --- °	MATERIAL NO. SEE CHART	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS							